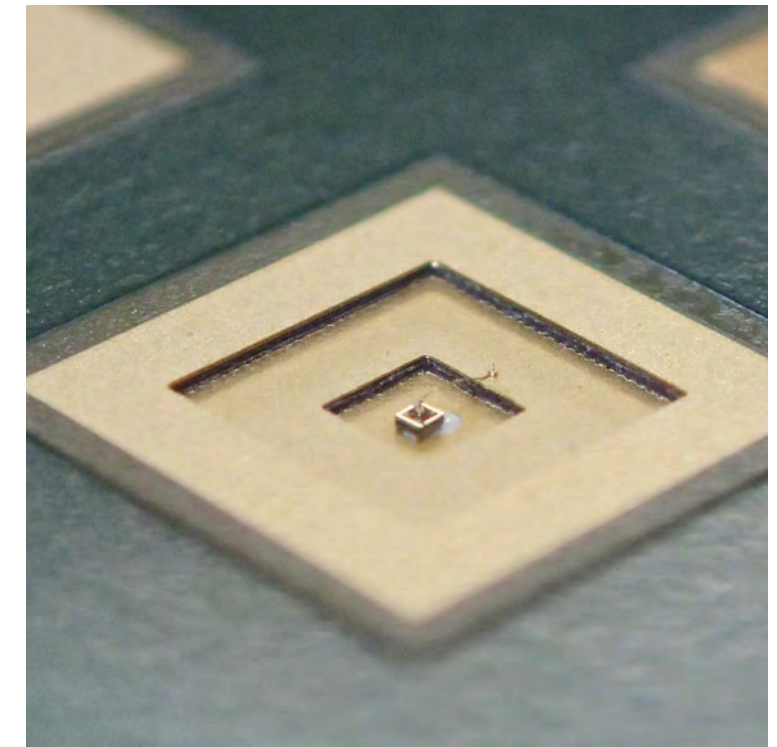
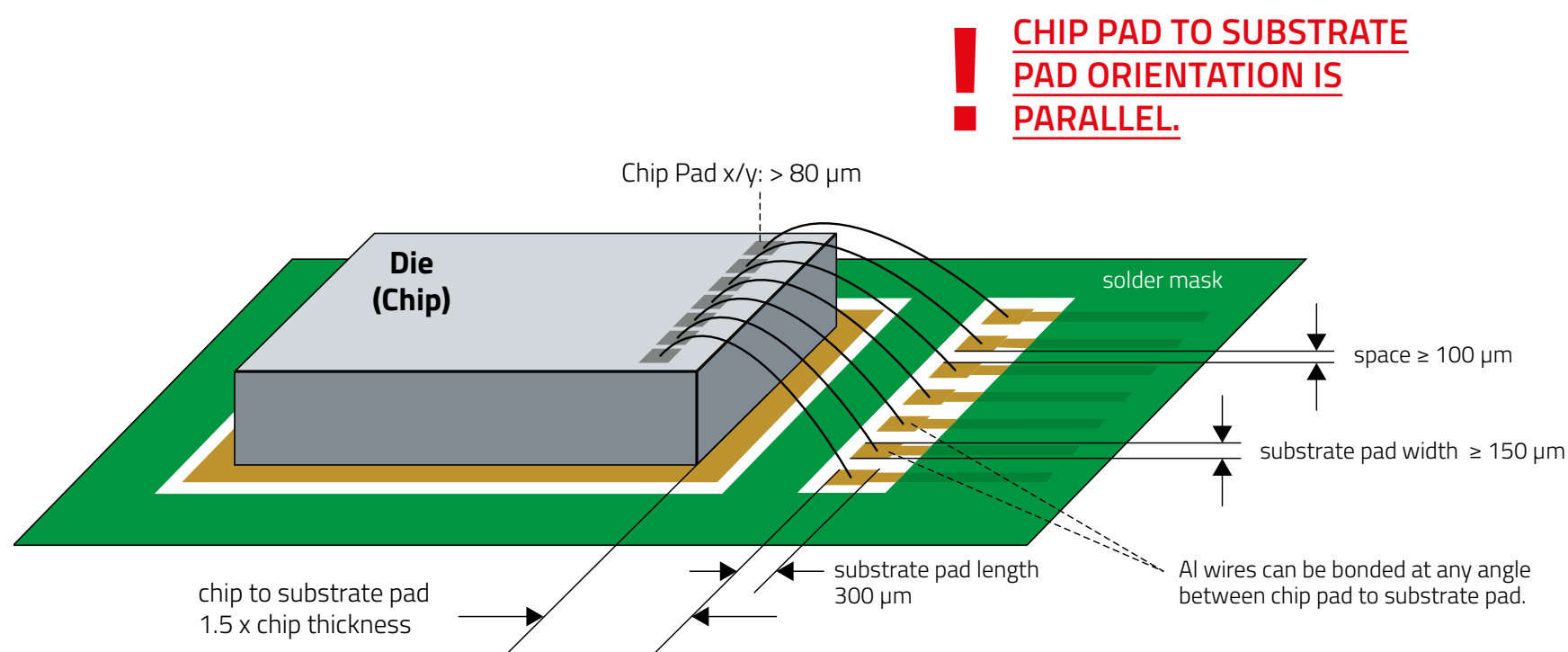


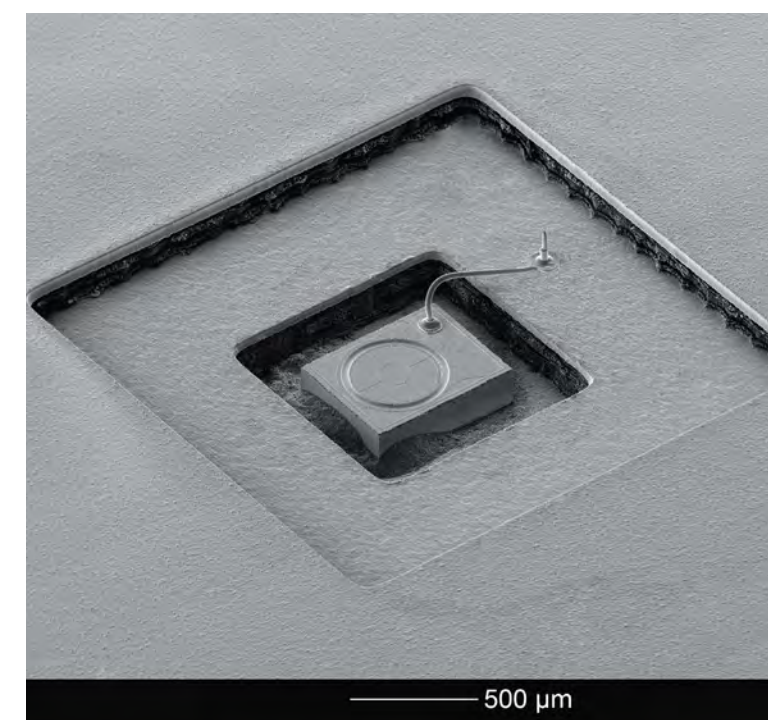
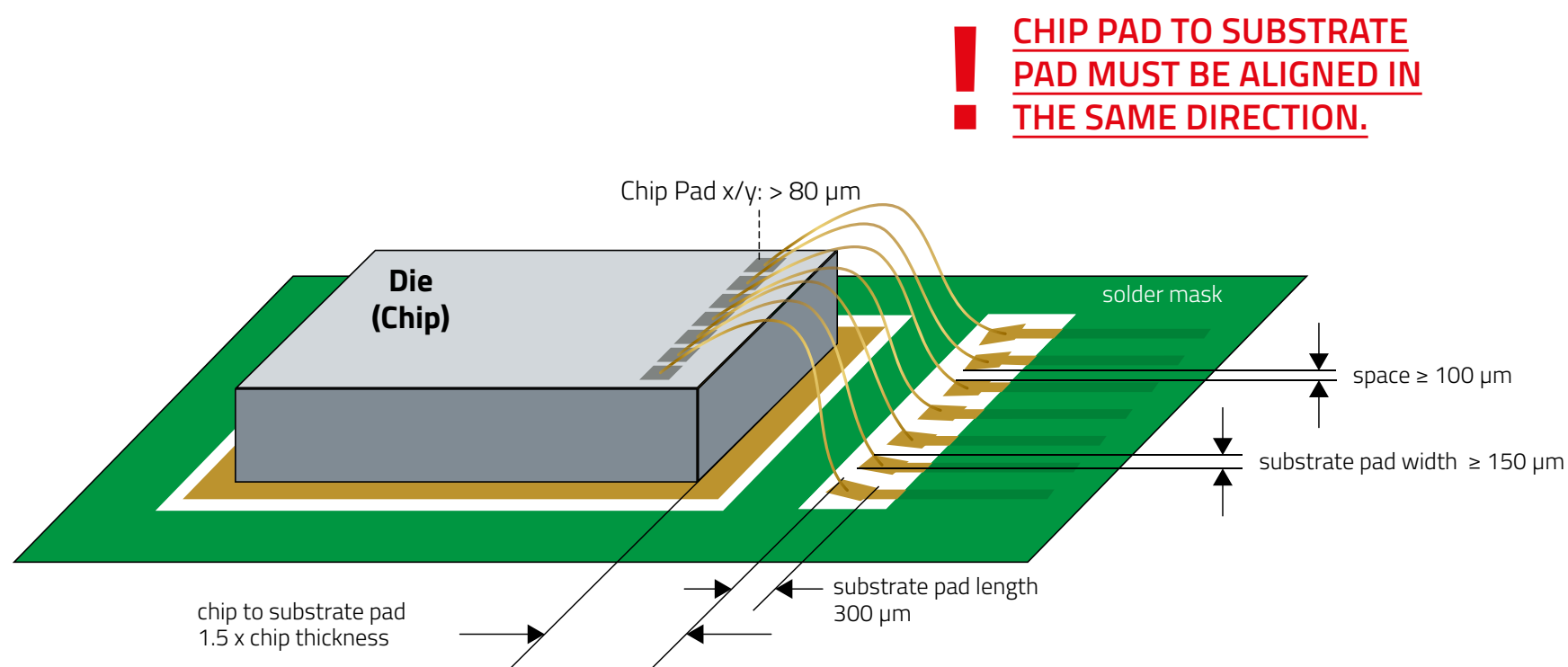
CHIP ON BOARD / WIRE BONDING

Design Rules for Aluminium (Al) wire bonding

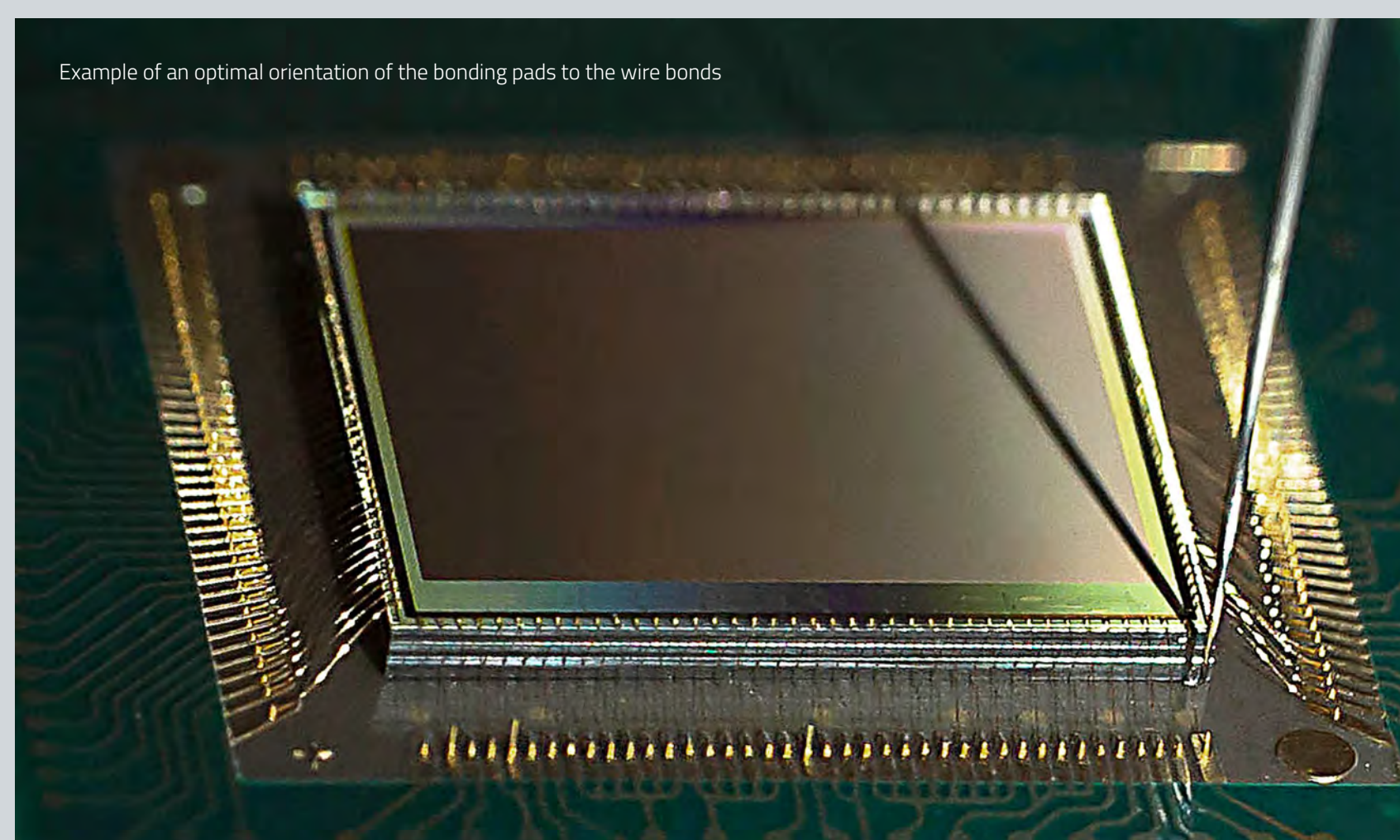


Wire bonded diode in a multi-step Lasercavity

Design Rules for Gold (Au) wire bonding



REM magnification of a wire bonded diode in a multi-step Lasercavity



Example of an optimal orientation of the bonding pads to the wire bonds

! THE SOLDER MASK MUST BE RELEASED AS BLOCK IN THE AREA OF THE BOND PADS!

MORE SUPPORT THAN YOU EXPECT

wirebonding@we-online.com

Do you have questions about fabrication data, tolerances, test documentation or packaging? In our Technical Delivery Specification for printed circuit boards (TDS) you will find our standards and recommendations for smooth and effective cooperation.